Green Journals

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Journal Information

Journal Title	IEEE TRANSACTIONS ON COMPONENTS PACKAGING AND MANUFACTURING TECHNOLOGY
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Classification History

Year	A+	A	B	C
2026		✓	✓	
2025		✓	✓	
2024		✓	✓	
2023		✓	✓	
2021/2022		✓	✓	
2020		✓	✓	
2019		✓	✓	
2018		✓		

Classification: The table above shows all journal classifications recorded for each classification year in the Green Journals database. A journal may have more than one classification in the same year.

Recent Articles

An Approach for Analyzing Far-End Crosstalk Between Microstrip Differential Pairs Using a Four-Port Network Analyzer
2026-10 Vol. 16 Issue 10 Pages 2339-2346
Authors: Juan P. Sánchez-Muñoz, Svetlana C. Sejas-García, Chudy Nwachukwu et al.
DOI: 10.1109/tcpmt.2026.3733979

An Aging Monitoring Method for IGBT Module Bond Wires Based on Frequency Characteristics of Transformer Neutral-Point Voltage
2026-10 Vol. 16 Issue 10 Pages 2406-2416
Authors: Mingxing Du, Weiyi Zhu, Jianguo Xin
DOI: 10.1109/tcpmt.2026.3732365

A DGTD-Based Field-Circuit Co-Simulation Framework for Analysis of Space–Time Encoded Metasurfaces
2026-10 Vol. 16 Issue 10 Pages 2390-2405
Authors: Ming Yu Xi, Yan Shi, Jun Xi Zhou et al.
DOI: 10.1109/tcpmt.2026.3733106

A Stacked-Glass Wafer-Level Antenna for W-Band Scalable Phased Arrays
2026-10 Vol. 16 Issue 10 Pages 2382-2389
Authors: Boshen Chen, Yapei Chen, Li Liu et al.
DOI: 10.1109/tcpmt.2026.3717381

IEEE Transactions on Components, Packaging and Manufacturing Technology Information for Authors
2026-10 Vol. 16 Issue 10 Pages C3-C3
DOI: 10.1109/tcpmt.2026.3739040

A Wideband and Highly Accurate Electrical Model of Arbitrary TSV Arrays and RDL Interconnections With Partial Inductance Method for 3-D ICs
2026-10 Vol. 16 Issue 10 Pages 2374-2381
Authors: Junyi Hu, Hao-Ran Zhu, Lin-Sheng Wu
DOI: 10.1109/tcpmt.2026.3697766

Neural Network-Assisted Constitutive Model Predicts Isothermal Compressive Stress Behavior of SAC305 Lead-Free Solder
2026-10 Vol. 16 Issue 10 Pages 2304-2310
Authors: Yijie Du, Shuai Zhang, Miao Zhu et al.
DOI: 10.1109/tcpmt.2026.3719297

Contactless Air-Filled Substrate Integrated Waveguide on Low-Cost PCB for D-Band Applications
2026-10 Vol. 16 Issue 10 Pages 2347-2359
Authors: Kaan Aktaş, Martin Petek, Enrico Tolin et al.
DOI: 10.1109/tcpmt.2026.3717541

IEEE Transactions on Components, Packaging and Manufacturing Technology Society Information
2026-10 Vol. 16 Issue 10 Pages C4-C4
DOI: 10.1109/tcpmt.2026.3739042

Enhanced Stability in TOSA via Thermistor-on-Chip and Bridge-Pad Wire-Bonding Design
2026-10 Vol. 16 Issue 10 Pages 2417-2422
Authors: Liang Zhang, Xiaochuan Xia, Haoran Ma et al.
DOI: 10.1109/tcpmt.2026.3729652